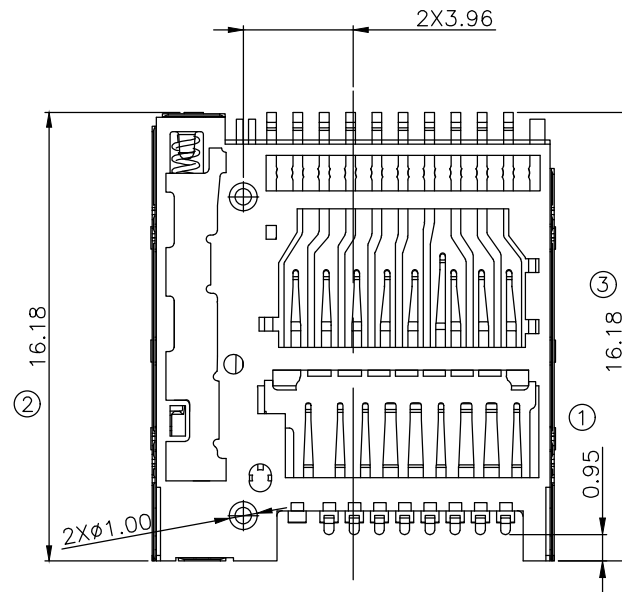
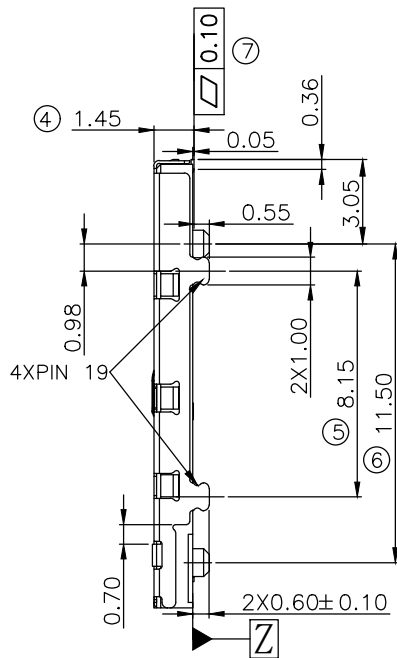
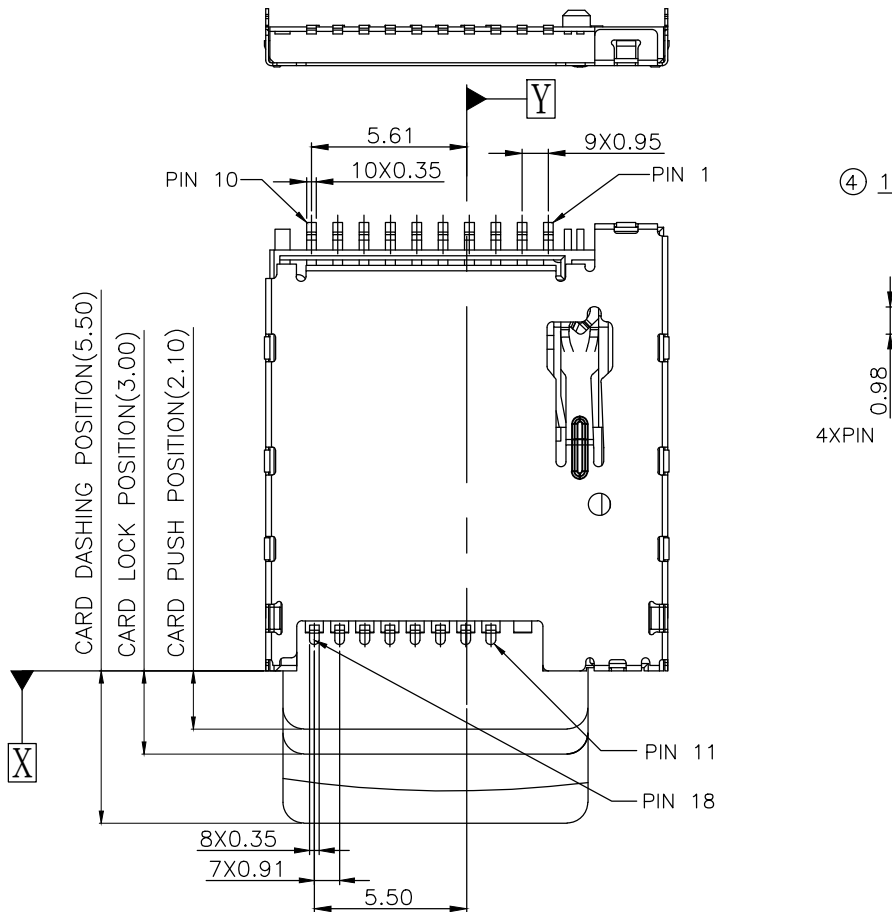


ROHS

ITEM	PART NAME	MATERIAL	NUM	COLOR	FINISHING	REMARK

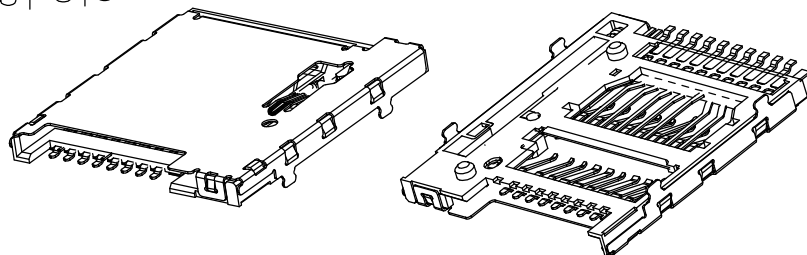


ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	LCP S475	Black UL94V-0,30% Glass Fiber
2	SLIDE	1	LCP E130i	Black UL94V-0,30% Glass Fiber
3	SHELL	1	SUS304 H T=0.10 $\pm$ 0.01	All Area: Ni 30-150u"
4	DATA CONTACT	1	C5191R-H T=0.10 $\pm$ 0.01	All Area: Ni 50-150u", Solder Tail: matte-tin 80-200u", Contact area: Au 1u"
5	SPRING	1	SWP-B	Ni 50u"
6	LINK	1	SUS304R-H	

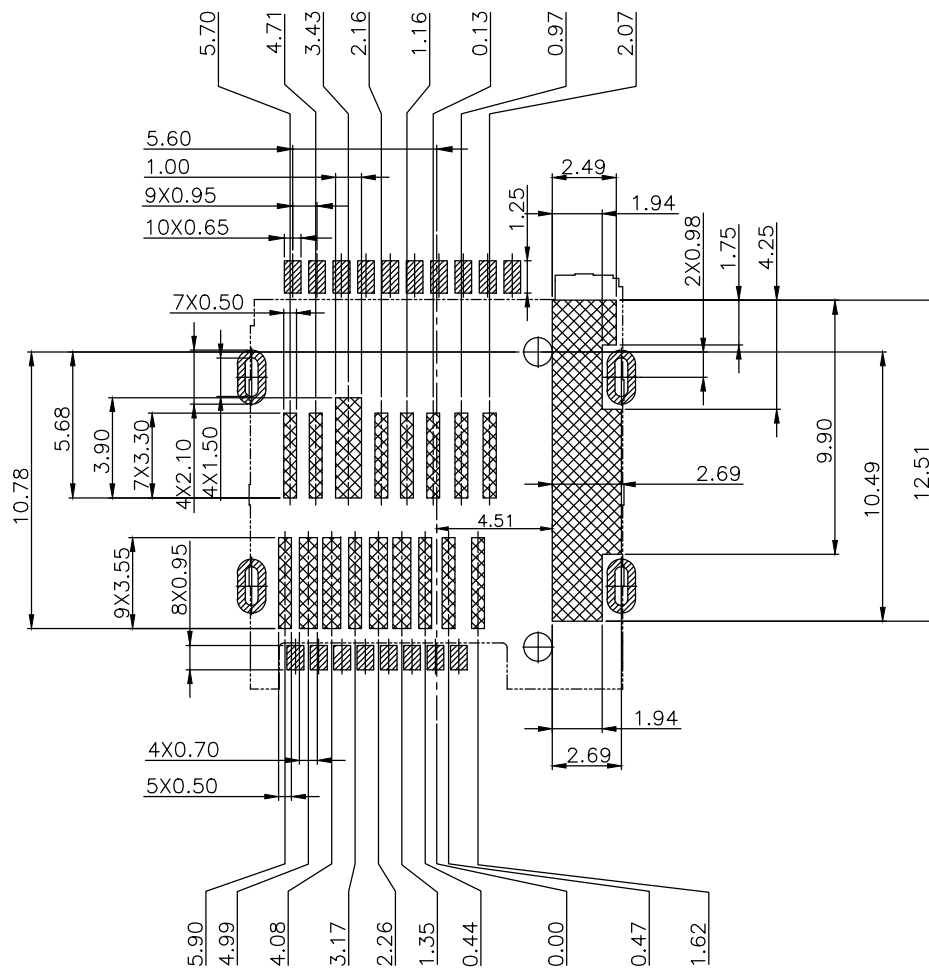
Part No: 2LS00P0017

REV.	REVISIONNOTE	DATE	TOLERANCE
A	新发行		X. $\pm$ 0.38 X.* $\pm$ 4* X.X $\pm$ 0.25 X.X* $\pm$ 2* X.XX $\pm$ 0.20 X.XXX $\pm$ 0.15
DRAWN	Wesker		PROJECTION
DES'D			
CHK'D			
APP'V'D			

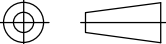
HJ-Tech 东莞市皇捷通讯科技有限公司 DONGGUAN HUANGJIE COMMUNICATION TECHNOLOGY CO., LTD.	
ARTICLE: MicroSD 40P-P	
MODEL	REV: A
SCALE: 1:1	UNIT: mm
SHEET:	



ITEM	PART NAME	MATERIAL	NUM	COLOR	FINISHING	REMARK



 PAD
 No trace, No test point,
 No via hole, No ground area

REV.	REVISIONNOTE	DATE	TOLERANCE		HJ-Tech 东莞市皇捷通讯科技有限公司 DONGGUAN HUANGJIE COMMUNICATION TECHNOLOGY CO., LTD.	
A	新发行		X. ± 0.38	X.* $\pm 4^{\circ}$		
			X.X ± 0.25	X.X* $\pm 2^{\circ}$		
			X.XX ± 0.20			
			X.XXX ± 0.15			
DRAWN		Wesker	PROJECTION		ARTICLE: M icroSD 40P-P	
DES'D						
CHK'D						
APP'VD			SCALE:	1: 1	UNIT:	mm
					SHEET:	
					MODEL	REV: A

ROHS

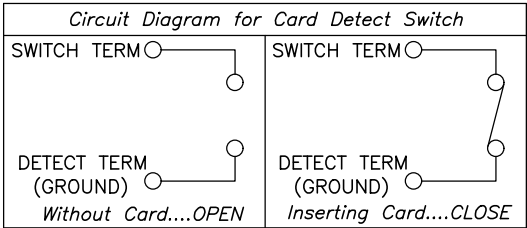
ITEM	PART NAME	MATERIAL	NUM	COLOR	FINISHING	REMARK

Pin Define

Connector PinNo.	MicroSD 4.0 Card Pin No.	Micro SD with UHS-II and SWIO support		
		Name	Type	Description
P1	P9	V _{DD2}	S	Supply voltage(1.8V)
P2	P1	DAT2	I/O	Data Line[Bit 2]
P3	P2	CD/DAT3	I/O	Card Detect/Data Line[Bit 3]
P4	P3	CMD	I/O	Command/Response
P5	P4	V _{DD1}	S	Supply voltage(3.3V)
P6	P5	CLK	I	Clock
P7		CD		
P8	P6	V _{SS}	S	Supply voltage ground
P9	P7	DAT0/RCLK+	I/O	Data Line[Bit 0]/RCLK+
P10	P8	DAT1/RCLK-	I/O	Data Line[Bit 1]/RCLK-
P11	P17	SWIO	I	Single Wire Protocol Interface
P12	P10	V _{SS}	S	Supply voltage ground
P13	P11	D0+	I/O	UHS-II D0+
P14	P12	D0-	I/O	UHS-II D0-
P15	P13	V _{SS}	S	Supply voltage ground
P16	P14	D1-	I/O	UHS-II D1-
P17	P15	D1+	I/O	UHS-II D1+
P18	P16	V _{SS}	S	Supply voltage ground
P19	GND		GROUND	

Specification

- *Electrical Characteristics:
Contact Current Rating:0.5 Amperes.
Dielectric Withstanding Voltage:AC500Vrms.
Insulation Resistance:1000 M Ω Minimum.
Contact Resistance:100 m Ω Maximum.
- *Environmental:
Operating Temperature: -25°C~+85°C.
- *Mechanical Characteristics:
Mating Cyeles:Office Environment 3,000 Cycles.
Harsh Environment 1.500 Cycles.
Total Insertion/Pulling Force:1.0N~80N.



REV.	REVISIONNOTE	DATE	TOLERANCE		Part No: 2LS00P0017 HJ-Tech 东莞市皇捷通讯科技有限公司 DONGGUAN HUANGJIE COMMUNICATION TECHNOLOGY CO., LTD. ARTICLE: MicroSD 4.0P-P MODEL REV: A
A	新发行		X. ± 0.38	X.* $\pm 4^{\circ}$	
			X.X ± 0.25	X.X* $\pm 2^{\circ}$	
			X.XX ± 0.20		
			X.XXX ± 0.15		
DRAWN Wesker			PROJECTION		
DES'D					
CHK'D					
APPV'D			SCALE: 1:1		UNIT: mm SHEET: